TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (U-MOSⅢ)

TPCP8203

Portable Equipment Applications

Motor Drive Applications

DC/DC Converters

- Lead (Pb)-free
- Small footprint due to small and thin package
- Low drain-source ON-resistance: $R_{DS(ON)}$ = 31 m Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 8.6 \text{ S}$ (typ.)
- Low leakage current: I_{DSS} = 10 μA (max)(V_{DS} = 40 V)
- Enhancement model: V_{th} = 1.3 to 2.5V
 - (V_{DS} = 10 V, I_D = 1 mA)

Absolute Maximum Ratings (Ta = 25°C)

Cha	racteristic	Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	40	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V _{DGR}	40	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	ID	4.7		
	Pulse (Note 1)	IDP	18.8		
Drain power	Single-device operation (Note 3a)	P _D (1)	1.48		
(t = 5 s) (Note 2a)	Single-device value at dual operation (Note 3b)	PD (2)	1.23		
Drain power dissipation (t = 5 s) (Note 2b)	Single-device operation (Note 3a)	P _{D (1)}	0.58		
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.36		
Single-pulse avala	nche energy (Note 4)	Eas	10.6	mJ	
Avalanche current		HAR	4.7	А	
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		EAR	0.12	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55 to 150	°C	

Note: For Notes 1 to 6, see the next page.

This transistor is an electrostatic-sensitive device. Handle with care.



Weight: 0.017 g (typ.)

Circuit Configuration



Marking (Note 6)



Thermal Characteristics

Characteristic		Symbol	Max	Unit	
Thermal resistance,	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	84.5	°C/W	
(t = 5 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	101.6		
Thermal resistance,	Single-device operation (Note 3a) Rth (ch-a) (1)		215.5	°C 1.11	
(t = 5 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	347.2	C/W	

Note 1: Ensure that the channel temperature does not exceed 150°C,

Note 2: (a) Device mounted on a glass-epoxy board (a)



(b) Device mounted on a glass-epoxy board (b)

Note 3: a) The power dissipation and thermal resistance values shown are for a single device. (During single-device operation, power is applied to one device only.)

- b) The power dissipation and thermal resistance values shown are for a single device. (During dual operation, power is applied to both devices evenly.).
- Note 4: $V_{DD} = 25 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$ (initial), $L = 0.5 \text{ mH}, \text{ R}_{G} = 25 \Omega, \text{ I}_{AR} = 4.7 \text{ A}$
- Note 5: Repetitive rating: Pulse width limited by Max. Channel temperature.
- Note 6: on the lower left of the marking indicates Pin 1.
 - * Weekly code (3 digits):

Week of manufacture

(01 for the first week of the year, continuing up to 52 or 53)

Year of manufacture

(The last digit of the calendar year)

Note 7: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS}=\pm 16~V,~V_{DS}=0~V$	_	_	±10	μA
Drain cutoff curre	nt	I _{DSS}	$V_{DS} = 40 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_	—	10	μA
Drain-source breakdown voltage		V (BR) DSS	I_D = 10 mA, V_{GS} = 0 V \checkmark	40	_	_	V
		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	15		_	v
Gate threshold voltage		V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	1.3		2.5	V
Drain-source ON-resistance		R _{DS (ON)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 2.4 \text{ A}$	Y,	43	60	mΩ
		R _{DS (ON)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 2.4 \text{ A}$	74	31	40	
Forward transfer admittance		Y _{fs}	V _{DS} = 10 V, I _D = 2.4A	4.3	8.6	—	S
Input capacitance		C _{iss}		> -	770	_	
Reverse transfer capacitance		C _{rss}	V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz	_	70	_	pF
Output capacitance		C _{oss}		_	105	-	
Switching time	Rise time	tr	$V_{GS} \stackrel{10 V}{}_{0 V}$	- (8		
	Turn-on time	t _{on}			15) —	ns
	Fall time	t _f			9	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, t _w = 10 µs	\mathbb{R}	70		
Total gate charge (gate-source plus	gate-drain)	Qg	$V_{DD} = 32 V. V_{CS} = 10 V.$	/_	16	_	
Gate-source charge1		Q _{gs1}	ID = 4.7 A	_	2.5	_	nC
Gate-drain ("Miller") charge		Q _{gd}		_	4	_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current Pulse (Note 1)	IDRP	(\vee) –	_	_	18.8	А
Forward voltage (diode)	VDSF	$I_{DR} = 4.7 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.2	V



TOSHIBA







RESTRICTIONS ON PRODUCT USE

The information contained herein is subject to change without notice.

20070701-EN GENERAL

TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and

set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc.
The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer personal equipment office equipment measuring equipment induction reliability ending the semiconductor reliability is applications.

- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in his document shall be made at the customer's own risk.
- The products described in this document shall not be used or embedded to any downstream products of which manufacture, use and/or sale are prohibited under any applicable laws and regulations.
- The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA for any infringements of patents or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any patents or other rights of TOSHIBA or the third parties.
- Please contact your sales representative for product-by-product details in this document regarding RoHS compatibility. Please use these products in this document in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances. Toshiba assumes no liability for damage or losses occurring as a result of noncompliance with applicable laws and regulations.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by Toshiba manufacturer:

Other Similar products are found below :

614233C 648584F MCH3443-TL-E MCH6422-TL-E FDPF9N50NZ FW216A-TL-2W FW231A-TL-E APT5010JVR NTNS3A92PZT5G IRF100S201 JANTX2N5237 2SK2464-TL-E 2SK3818-DL-E FCA20N60_F109 FDZ595PZ STD6600NT4G FSS804-TL-E 2SJ277-DL-E 2SK1691-DL-E 2SK2545(Q,T) D2294UK 405094E 423220D MCH6646-TL-E TPCC8103,L1Q(CM 367-8430-0972-503 VN1206L 424134F 026935X 051075F SBVS138LT1G 614234A 715780A NTNS3166NZT5G 751625C 873612G IRF7380TRHR IPS70R2K0CEAKMA1 RJK60S3DPP-E0#T2 RJK60S5DPK-M0#T0 APT5010JVFR APT12031JFLL APT12040JVR DMN3404LQ-7 NTE6400 JANTX2N6796U JANTX2N6784U JANTXV2N5416U4 SQM110N05-06L-GE3 SIHF35N60E-GE3